

	Type	L #	Hits	Search Text	DBs	Time Stamp	Error Count	Error Detail
1	BRS	L1	3	(cmp or "chemical mechanical polishing") same iminodiacetic	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 08:45	0	
2	BRS	L8	3	(cmp or "chemical mechanical polishing" same polish\$3) same iminodiacetic	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 08:46	0	
3	BRS	L15	11	(cmp or "chemical mechanical polishing" or polish\$3 or planariz\$5) same iminodiacetic	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 09:52	0	
4	BRS	L22	655	(cmp or "chemical mechanical polishing" or polish\$3 or planariz\$5) same (PVA or "polyvinyl alcohol" or "polyethylene oxide" or "polypropylene oxide" or "sulfonate polymer" or "sulfonic acid polymer")	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:06	0	
5	BRS	L29	461	22 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:06	0	
6	BRS	L36	40	22 same semiconductor	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 09:59	0	
7	BRS	L43	14	36 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:07	0	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Error Count	Correlation
8	BRS	L50	9	29 and 438/\$.ccls.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:07	0	
9	BRS	L57	21	29 and 252/\$.ccls.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:07	0	
10	BRS	L71	21	57 and 252/\$.ccls.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:10	0	
11	BRS	L64	9	50 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:10	0	
12	BRS	L78	19	71 not 64	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 10:13	0	
13	BRS	L92	11	(cmp or "chemical mechanical polishing" or polish\$3 or planariz\$5) same (iminodiacetic)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:50	0	
14	BRS	L99	40	(abrasive or slurry) same (iminodiacetic)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:50	0	

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r D e f e r e n t i t i o n
15	BRS	L106	22	99 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:52		0
16	BRS	L113	55	(abrasive or slurry) same (iminodiacetic or ida)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:50		0
17	BRS	L120	22	(cmp or "chemical mechanical polishing" or polish\$3 or planariz\$5) same (iminodiacetic or ida)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:51		0
18	BRS	L127	8	120 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:51		0
19	BRS	L134	35	113 and @pd<=19990810	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2002/06/12 13:53		0